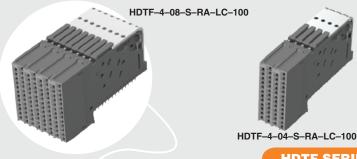


XCede HD



(1.80 mm) .071"

HDTF SERIES

(1.80)

XCede® HD BACKPLANE RECEPTACLE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDTF

Insulator Material: Liquid Crystal Polymer Contact Material: Copper Alloy Plating:

Copper Alloy
Plating:
Sn or Au over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-40 °C to +105 °C
Current Rating:
Testing Now!
RoHS Compliant:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



TOOLING

 For press-fit extraction and insertion tool options, visit www.samtec.com/tooling

Mates with:

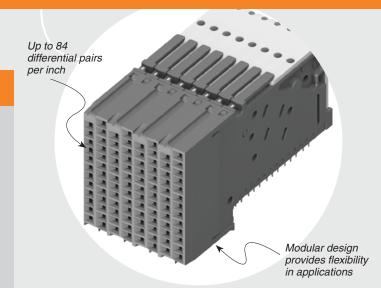
HDTM

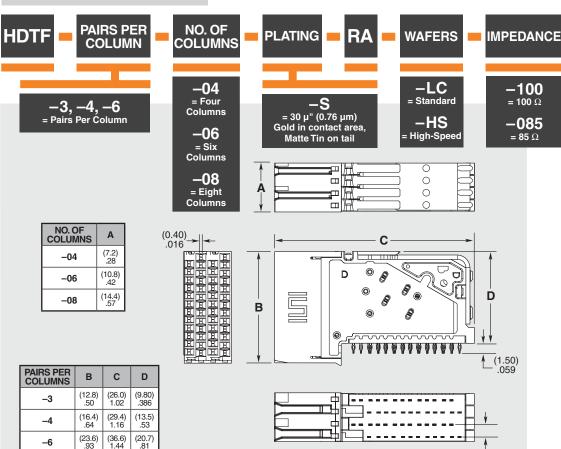
ALSO AVAILABLE (Customer Defined Configurations)



Power and keying/guidance modules also are available but require a single customizable BSP product. A BSP product is built by combining any number, in any configuration, of HDTFs, power and keying/guidance modules to create one receptacle.

Contact HSBP@samtec.com for more information about building a BSP product.





XCede® is a registered trademark of Amphenol.

Due to technical progress, all designs, specifications and components are subject to change without notice.